

Entrusted Items Concerning Preparation of Draft Proposals for JIS

Newly Established

Divisional Council	T i t l e	Assigned Organization	Contact
Iron and Steel	Non-destructive testing -- Penetrant testing—Part5:Penetrant testing at temperatures higher than 50	The Japanese Society for Non-Destructive Inspection	A
Iron and Steel	Non-destructive testing -- Penetrant testing—Part6:Penetrant testing at temperatures lower than 10	The Japanese Society for Non-Destructive Inspection	A
Chemical Products	Adhesives-Method of preparing bulk specimens - Part1 Two-part systems	The Japan Plastics Industry Federation	A
Chemical Products	Adhesives-Method of preparing bulk specimens - Part2 Elevated - temperature-curing one-part systems	The Japan Plastics Industry Federation	A
Chemical Products	Elastomeric seismic-protection isolators for buildings -- Specificatons	Japan Rubber Manufacturers Association	A
Chemical Products	Elastomeric seismic-protection isolators for buildings -- Test methods	Japan Rubber Manufacturers Association	A
Machine Elements	Gears - Evaluation of instruments for the measurement of individual gears	Japan Gear Manufacturers Association	A
Steel	Metallic materials - Sheet and strip - Hole expanding test	The Japan Iron and Steel Federtion	A
Nonferrous Materials and Metallurgy	Testing method for coefficient of linear expansion of thermal barrier coatings	Osaka Science & Technology Center	A
Nonferrous Materials and Metallurgy	Measurement method for thermal conductivity of thermal barrier coating	Osaka Science & Technology Center	A
Nonferrous Materials and Metallurgy	Testing Methods for Young's Modulus of Thermal Barrier Coatings	Osaka Science & Technology Center	A
Medical Equipment	Elastomeric auxiliaries for use in orthodontics	THE JAPAN STAPLE, NAIL AND TOOL	B
Medical Equipment	Dental metallic materials - Test methods	THE JAPAN STAPLE, NAIL AND TOOL	B

Medical Equipment	Sterilization of health care products –Chemical indicators – Part 1:General requirements	Japanese Society of Medical Instrumentation	B
Medical Equipment	Sterilization of medical devices –Microbiological methods – Part 1:Determination of a population of microorganisms on products	Japanese Society of Medical Instrumentation	B
Assistive Technology	Turning aids	Japan assistive products association	B
Electrical Technology	Electrical insulating materials - Properties of thermal endurance – Part 1: Aging procedures and evaluation of test results	The Institute of Electrical Engineers of Japan	B
Electrical Technology	Electrical insulating materials - Properties of thermal endurance – Part 2: Choice of test criteria for determination of thermal endurance	The Institute of Electrical Engineers of Japan	B
Older persons and persons with disabilities	Guidelines for people including elderly and people with disabilities - Tactile information - Basic design methods for Tactile Patterns	National Institute of Advanced Industrial Science and Technology	B
Electronics	Fixed capacitors for use in electronic equipment - Part 26: Sectional specification - fixed aluminium electrolytic capacitors with conductive polymer solid electrolyte	Japan Electronics & Information Tecnology Industries Association	C
Electronics	Fixed capacitors for use in electronic equipment - Part 26-1: Blank detail specification - Aluminium electrolytic capacitors with conductive polymer solid electrolyte	Japan Electronics & Information Tecnology Industries Association	C
Electronics	Connectors for electronic equipment - Tests and measurements - Part 13-2: Mechanical operation tests - Test 13b: Insertion and withdrawal forcesk	Japan Electronics & Information Tecnology Industries Association	C
Electronics	Connectors for electronic equipment - Tests and measurements - Part 16-2: Mechanical tests on contacts and terminations - Test 16b: Restricted entry	Japan Electronics & Information Tecnology Industries Association	C
Electronics	Connectors for electronic equipment - Tests and measurements - Part 16-4: Mechanical tests on contacts and terminations - Test 16d: Tensile strength (crimped connections)	Japan Electronics & Information Tecnology Industries Association	C
Electronics	Connectors for electronic equipment - Tests and measurements - Part 16-5: Mechanical tests on contacts and terminations - Test 16e: Gauge retention force (resilient contacts)	Japan Electronics & Information Tecnology Industries Association	C
Electronics	Connectors for electronic equipment - Tests and measurements - Part 16-7: Mechanical tests on contacts and terminations - Test 16g: Measurement of contact deformation after crimping	Japan Electronics & Information Tecnology Industries Association	C

Electronics	Optical amplifiers - Test methods - Part 10-3:Multichannel parameters - Probe method	OPTOELECTRONIC INDUSTRY AND TECHNOLOGY DEVELOPMENT ASSOCIATION	C
Electronics	Test methods of polarizer	OPTOELECTRONIC INDUSTRY AND TECHNOLOGY DEVELOPMENT ASSOCIATION	C
Electronics	Fiber optic interconnecting devices and passive components – Basic test and measurement procedures - Part 2-22: Tests - Change of temperature	OPTOELECTRONIC INDUSTRY AND TECHNOLOGY DEVELOPMENT ASSOCIATION	C
Electronics	Fiber optic interconnecting devices and passive components – Basic test and measurement procedures - Part 3-2: Examinations and measurements - Polarization dependent loss in a single-mode fiber optic	OPTOELECTRONIC INDUSTRY AND TECHNOLOGY DEVELOPMENT ASSOCIATION	C
Electronics	Fiber optic connector interfaces - Part5:Type MT connector family	OPTOELECTRONIC INDUSTRY AND TECHNOLOGY DEVELOPMENT ASSOCIATION	C
Electronics	Fiber optic interconnecting devices and passive components – Basic test and measurement procedures – Part 3-16: Examinations and measurements – Endface radius of spherically polished ferrules	OPTOELECTRONIC INDUSTRY AND TECHNOLOGY DEVELOPMENT ASSOCIATION	C
Electronics	Fiber optic interconnecting devices and passive components – Basic test and measurement procedures – Part 3-27: Examinations and measurements – Measurement method for the hole location of a	OPTOELECTRONIC INDUSTRY AND TECHNOLOGY DEVELOPMENT ASSOCIATION	C
Electronics	Fiber optic interconnecting devices and passive components – Basic test and measurement procedures – Part 3-36: Examinations and measurements – Measurement methods for the inside and outside diameters of fiber optic connector ferrules	OPTOELECTRONIC INDUSTRY AND TECHNOLOGY DEVELOPMENT ASSOCIATION	C
Electronics	Fiber optic communication subsystem test rcedures – Digital systems – Time-resolved chirp and alpha-factor measurement of laser transmitters	OPTOELECTRONIC INDUSTRY AND TECHNOLOGY DEVELOPMENT ASSOCIATION	C
Information Technology	Information technology – 120 mm (8,54 Gbytes per side) and 80 mm (2,66 Gbytes per side) DVD recordable disk for dual layer (DVD-R for DL)	OPTOELECTRONIC INDUSTRY AND TECHNOLOGY DEVELOPMENT ASSOCIATION	C
Information Technology	Universal Disk Format (UDF) 2.00	OPTOELECTRONIC INDUSTRY AND TECHNOLOGY DEVELOPMENT ASSOCIATION	C
Information Technology	Scalable Vector Graphics (SVG) Tiny 1.2 Specification	Japan Information Processing Development Corporation	C

Electronics	Fiber optic interconnecting devices and passive components- Basic test and measurement procedures- Part 3-30: Examinations and measurements- Polish angle and fiber position on single ferrule multifiber connectors	Optoelectronic Industry and Technology Development Association	C
Electronics	Test methods of polarizer	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic interconnecting devices and passive components- Basic test and measurement procedures- Part 2-22: Tests - Change of temperature	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic interconnecting devices and passive components- Basic test and measurement procedures- Part 3-2: Examinations and measurements - Polarization dependent loss in a single-mode fiber optic device	Optoelectronic Industry and Technology Development Association	C
Electronics	Optical amplifiers - Test methods - Part 10-3: Multichannel parameters - Probe method	Optoelectronic Industry and Technology Development Association	C
	Fiber optics connector interfaces - Part5:Type MT connector family (F12)	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic interconnecting devices and passive components- Basic test and measurement procedures- Part 3-16: Examinations and measurements - Endface radius of spherically polished ferrules	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic interconnecting devices and passive components- Basic test and measurement procedures- Part 3-27: Measurement method for the hole location of a multiway connector plug	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic interconnecting devices and passive components- Basic test and measurement procedures- Part 3-36: Measurement methods for the insite and outside diameters of fiber optic connector ferrules	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic communication subsystem test procedures - Time-resolved chirp and alpha-factor measurement of laser transmitters	Optoelectronic Industry and Technology Development Association	C
Electronics	Optical fiber cables-Parts 3-10:Outdoor cables-Family specification for duct and directly buried optical telecommunication cables	Optoelectronic Industry and Technology Development Association	C
Electronics	Optical fiber cables-Parts 3-20:Outdoor cables-Optical self-supporting aerial telecommunication outdoor cables	Optoelectronic Industry and Technology Development Association	C

Electronics	Fiber optic interconnecting devices and passive components-Basic test and measurement procedures-Part 3-6: Examinations and measurements-Return loss	Optoelectronic Industry and Technology Development Association	C
Electronics	Performance standard of optic pigtailed style isolators	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic interconnecting devices and passive components-Basic test and measurement procedures-Part 2-12: Tests-impact	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic interconnecting devices and passive components-Basic test and measurement procedures-Part 2-14: Tests-Optical power handling and damage threshold characterization	Optoelectronic Industry and Technology Development Association	C
Electronics	Non connectorised single-mode fiber optic 980/1550nm WDM devices	Optoelectronic Industry and Technology Development Association	C
Electronics	Non connectorised single-mode fiber optic C-band/L-band WDM devices	Optoelectronic Industry and Technology Development Association	C
Electronics	Analysis techniques for system reliability-Procedure for failure mode and effects analysis(FMEA)	Japanese Standard Association	C
Electronics	Fiber optic interconnecting devices and passive components-Basic test and measurement procedures-Part 2-2: Mating durability	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic interconnecting devices and passive components-Basic test and measurement procedures-Part 3-4: Attenuation	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic interconnecting devices and passive components-Basic test and measurement procedures-Part 2-46: Tests-Damp heat, cyclic	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic interconnecting devices and passive components-Basic test and measurement procedures-Part 2-47: Tests-Thermal shocks	Optoelectronic Industry and Technology Development Association	C
Electronics	Optical amplifiers - Test methods - Part 1-1: Power and gain parameters-Optical spectrum analyzer method	Optoelectronic Industry and Technology Development Association	C
Electronics	Optical amplifiers - Test methods - Part 1-2: Power and gain parameters-Electrical spectrum analyzer method	Optoelectronic Industry and Technology Development Association	C
Electronics	Optical amplifiers - Test methods - Part 1-3: Power and gain parameters-Optical power meter method	Optoelectronic Industry and Technology Development Association	C
Electronics	Optical amplifiers - Test methods - Part 3: Noise figure parameters	Optoelectronic Industry and Technology Development Association	C
Electronics	Optical amplifiers - Test methods - Part 3-1: Noise figure parameters-Optical spectrum analyzer method	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic connector optical interfaces-Part 2-1: Optical interface standard single mode non-angled physically contacting fibers	Optoelectronic Industry and Technology Development Association	C

Electronics	Fiber optic connector optical interfaces-Part 2-2: Optical interface standard single mode angled physically contacting fibers	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic connector optical interfaces-Part 3-1: Optical interface, 2.5mm and 1.25mm diameter cylindrical full zirconia PC ferrule, single	Optoelectronic Industry and Technology Development Association	C
Electronics	Fiber optic connector optical interfaces-Part 3-1: Optical interface, 2.5mm and 1.25mm diameter cylindrical full zirconia ferrules for 8 degrees angled-PC single mode fibers	Optoelectronic Industry and Technology Development Association	C
Electronics	General rules of fiber optic WDM devices	Optoelectronic Industry and Technology Development Association	C
Electronics	Fault Tree Analysis(FTA)	Japanese Standard Association	C